| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| 7 | 33 | 5426563.URPN. | USPAT | 2003/07/16 15:11 |
| 8 | 13 | 5426563.URPN. and (cool$3 with (liquid$1 fluid$1)) | USPAT | 2003/07/16 15:56 |
| 9 | 149 | (((printed with circuit with board$1) semiconductor) with test$3) and (cool$3 (temperature with control$4)) and ((test adj head) testhead) | USPAT | 2003/07/16 15:59 |
| 10 | 51 | ((((printed with circuit with board$1) semiconductor) with test$3) and (cool$3 (temperature with control$4)) and ((test adj head) testhead)) and (computer) | USPAT | 2003/07/16 16:00 |
| 11 | 7 | (((((printed with circuit with board$1) semiconductor) with test$3) and (cool$3 (temperature with control$4)) and ((test adj head) testhead)) and (computer)) and (parallel with (board$1 card$1)) | USPAT | 2003/07/16 16:58 |
| 12 | 1 | 6052284.pn. | USPAT | 2003/07/16 16:58 |
| - | 7 | ((printed with circuit$2 with board$1) (channel with card$1)) and (semiconductor with (test$3 cool$3)) and ((board$1 card$1) with parallel) and ((board$1 card$1) with border) | USPAT | 2003/07/16 11:35 |
| - | 389 | ((printed with circuit$2 with board$1) (channel with card$1)) and ((board$1 card$1) with parallel) and ((board$1 card$1) with (border seal)) | USPAT | 2003/07/14 11:19 |
| - | 31 | (((printed with circuit$2 with board$1) (channel with card$1)) and ((board$1 card$1) with parallel) and ((board$1 card$1) with (border seal))) and (semiconductor with (test$3 cool$3)) | USPAT | 2003/07/14 11:21 |
| - | 0 | ((((printed with circuit$2 with board$1) (channel with card$1)) and ((board$1 card$1) with parallel) and ((board$1 card$1) with (border seal))) and ((liquid air) with tight with (container border seal mount$3))) and (semiconductor with (test$3 cool$3)) | USPAT | 2003/07/14 11:21 |
| - | 14 | (((printed with circuit$2 with board$1) (channel with card$1)) and ((board$1 card$1) with parallel) and ((board$1 card$1) with (border seal))) and ((liquid air) with tight with (container border seal mount$3)) | USPAT | 2003/07/14 11:23 |
| - | 0 | ((((printed with circuit$2 with board$1) (channel with card$1)) and ((board$1 card$1) with parallel) and ((board$1 card$1) with (border seal))) and (semiconductor with (test$3 cool$3))) and ((liquid air) with tight with (container border seal mount$3)) | USPAT | 2003/07/14 11:23 |
| - | 12 | ((printed with circuit$2 with board$1) (channel with card$1)) and ((board$1 card$1) with parallel with mount$3) and ((seal border) with (air liquid) with tight) | USPAT | 2003/07/14 11:28 |
| - | 14 | ((printed with circuit$2 with board$1) (channel with card$1)) and ((semiconductor$1 board$1 card$1) with (stack$4 parallel) with mount$3) and ((seal border) with (air liquid) with tight) | USPAT | 2003/07/14 11:34 |
| - | 27 | (parallel with circuit$2 with board$1) and (liquid with tight with (border wall seal$1)) | USPAT | 2003/07/14 11:42 |

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|---|---|---|---|---|---|
| – | | 0 | ((parallel with circuit$2 with board$1) and (liquid with tight with (border wall seal$1))) and (non-conduct$3 with (liquid$1 fluid$1)) | USPAT | 2003/07/14 11:43 |
| – | | 7 | ((parallel with circuit$2 with board$1) and (liquid with tight with (border wall seal$1))) and ((insulat$3 cool$3) with (liquid$1 fluid$1)) | USPAT | 2003/07/14 12:09 |
| – | | 4 | (semiconductor with test$3 with cool$3) and (parallel with ((circuit with board$1) (channel with card$1) (circuit with card$1))) | USPAT | 2003/07/14 12:13 |
| – | | 3 | ((semiconductor with test$3 with cool$3) and (parallel with ((circuit with board$1) (channel with card$1) (circuit with card$1)))) and ((liquid$1 fluid$1) with cool$3) | USPAT | 2003/07/15 12:06 |
| – | | 7 | 6052284.URPN. | USPAT | 2003/07/15 11:22 |
| – | | 279 | (printed with circuit with cool$3) and ((liquid cool$3 fluid) with (chamber container)) | USPAT | 2003/07/14 12:27 |
| – | | 23 | ((printed with circuit with cool$3) and ((liquid cool$3 fluid) with (chamber container))) and ((chamber container) with (boundary wall border)) and (parallel with (board$1 semiconductor$1 card$1)) | USPAT | 2003/07/14 12:29 |
| – | | 3 | (((printed with circuit with cool$3) and ((liquid cool$3 fluid) with (chamber container))) and ((chamber container) with (boundary wall border)) and (parallel with (board$1 semiconductor$1 card$1))) and (non with conduct$4 with (liquid$1 fluid$1 coolant)) | USPAT | 2003/07/14 12:30 |
| – | | 23 | ("4092697" \| "4138692" \| "4381032" \| "4531146" \| "4807019" \| "4879629" \| "5195020" \| "5224017" \| "5294830" \| "5306866" \| "5349498" \| "5388635" \| "5638597" \| "5656862" \| "5658831" \| "5668059" \| "5727310" \| "5786629" \| "5838060" \| "6052284" \| "6165596" \| "6208517" \| "6271058").PN. | USPAT | 2003/07/15 11:18 |
| – | | 15 | (("4092697" \| "4138692" \| "4381032" \| "4531146" \| "4807019" \| "4879629" \| "5195020" \| "5224017" \| "5294830" \| "5306866" \| "5349498" \| "5388635" \| "5638597" \| "5656862" \| "5658831" \| "5668059" \| "5727310" \| "5786629" \| "5838060" \| "6052284" \| "6165596" \| "6208517" \| "6271058").PN.) and (cool$3 with (fluid$1 liquid$1)) | USPAT | 2003/07/15 11:22 |
| – | | 4 | (("4092697" \| "4138692" \| "4381032" \| "4531146" \| "4807019" \| "4879629" \| "5195020" \| "5224017" \| "5294830" \| "5306866" \| "5349498" \| "5388635" \| "5638597" \| "5656862" \| "5658831" \| "5668059" \| "5727310" \| "5786629" \| "5838060" \| "6052284" \| "6165596" \| "6208517" \| "6271058").PN.) and (cool with (fluid$1 liquid$1)) | USPAT | 2003/07/15 11:46 |
| – | | 4 | (second with circuit with board) and (parallel$2 with mount$3 with board$1) and ((liquidtight (liquid adj tight) (air adj tight)) with (border boundary wall container)) | USPAT | 2003/07/15 14:09 |
| – | | 332 | first with second with circuit$1 with boards$1 with parallel$3 | USPAT | 2003/07/15 14:11 |

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|---|---|---|---|---|---|
| – | | 30 | (first with second with circuit$1 with boards$1 with parallel$3) and (first and second with (border boundary wall) with (between interposed connecting)) | USPAT | 2003/07/15 14:20 |
| – | | 31 | (first with second with circuit$1 with boards$1 with parallel$3) and (first and second with (border boundary wall seal) with (between interposed connecting)) | USPAT | 2003/07/15 14:27 |
| – | | 0 | ((first with second with circuit$1 with boards$1 with parallel$3) and (first and second with (border boundary wall seal) with (between interposed connecting))) and ((liquidtight (liquid adj tight) (air adj tight)) with (border boundary wall container seal)) | USPAT | 2003/07/15 14:27 |
| – | | 0 | ((first with second with circuit$1 with boards$1 with parallel$3) and (first and second with (border boundary wall seal) with (between interposed connecting))) and (liquidtight (liquid adj tight) (air adj tight)) | USPAT | 2003/07/15 14:22 |
| – | | 14 | ((first with second with circuit$1 with boards$1 with parallel$3) and (first and second with (border boundary wall seal) with (between interposed connecting))) and (liquid$1 fluid$1) | USPAT | 2003/07/15 14:28 |
| – | | 4 | ((first with second with circuit$1 with boards$1 with parallel$3) and (first and second with (border boundary wall seal) with (between interposed connecting))) and ((liquid$1 fluid$1) with cool$3) | USPAT | 2003/07/15 14:29 |
| – | | 72 | ((liquid$1 fluid$1) with cool$3 with parallel with ((circuit adj board$1) semiconductor$1)) | USPAT; EPO; JPO; DERWENT | 2003/07/15 14:39 |
| – | | 15 | (((liquid$1 fluid$1) with cool$3 with parallel with ((circuit adj board$1) semiconductor$1))) and ((border seal wall) with (between interposed seperat$3)) | USPAT; EPO; JPO; DERWENT | 2003/07/15 14:41 |
| – | | 3 | 5835349.URPN. | USPAT | 2003/07/15 16:39 |
| – | | 24 | (border wall seal) with (between interposed) with parallel with ((circuit adj boards) (channel adj card$1) pcb$2) | USPAT | 2003/07/15 17:16 |
| – | | 2 | ((border wall seal) with (between interposed) with parallel with ((circuit adj boards) (channel adj card$1) pcb$2)) and ((liquid$1 fluid$1) with cool$3) | USPAT | 2003/07/15 17:18 |
| – | | 11 | (parallel with circuit with board$1 with form$3 with (liquid$1 fluid$1) with (chamber container cool$3)) | USPAT; EPO; JPO; DERWENT | 2003/07/15 17:47 |
| – | | 28 | printed with circuit with board$1 with test$3 with cool$3 | USPAT | 2003/07/16 11:42 |
| – | | 110 | 324/514.ccls. | USPAT | 2003/07/16 11:37 |
| – | | 0 | 324/514.ccls. and (printed with circuit$2 with board$1) and ((liquid$1 fluid$1) with Cool$3) | USPAT | 2003/07/16 11:38 |
| – | | 3 | 324/514.ccls. and ((liquid$1 fluid$1) with Cool$3) | USPAT | 2003/07/16 11:38 |
| – | | 7 | 324/514.ccls. and (printed with circuit$2 with board$1) | USPAT | 2003/07/16 11:39 |
| – | | 534 | (printed with circuit with board$1) and (test$3 with cool$3) | USPAT | 2003/07/16 11:43 |
| – | | 15 | ((printed with circuit with board$1) and (test$3 with cool$3)) and (second with circuit with board$1) and ((border seal wall) with (between interposed connect$3)) | USPAT | 2003/07/16 11:48 |

| - | 7 | (((printed with circuit with board$1) and (test$3 with cool$3)) and (second with circuit with board$1) and ((border seal wall) with (between interposed connect$3))) and (liquid$1 fluid$1) | USPAT | 2003/07/16 12:22 |
| - | 28 | ((semiconductor$1 substrate) with parallel with form$3 with ((liquid$1 fluid$1) with cool$3)) | USPAT | 2003/07/16 12:24 |
| - | 7 | (((semiconductor$1 substrate) with parallel with form$3 with ((liquid$1 fluid$1) with cool$3))) and (test$3) | USPAT | 2003/07/16 15:11 |

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